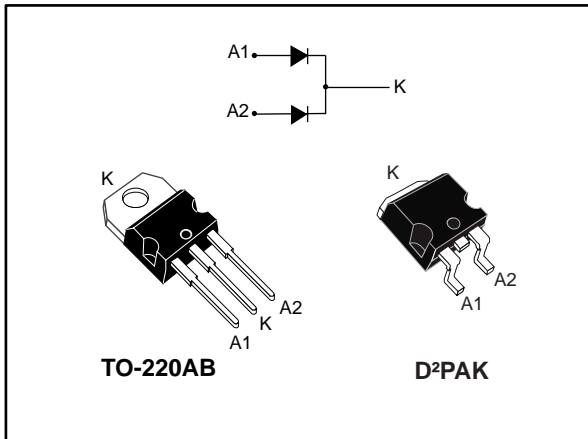


## 60 V field-effect rectifier diode

Datasheet - production data



### Description

The device is based on a proprietary technology that achieves the best in class  $V_F/I_R$  trade-off for a given silicon surface.

This 60 V rectifier has been optimized for use in confined applications where both efficiency and thermal performance are key.

This device is suitable for use in adapters and chargers.

Table 1: Device summary

Symbol	Value
$I_{F(AV)}$	2 x 15 A
$V_{RRM}$	60 V
$V_F$ (typ.)	0.37 V
$T_j$ (max.)	150 °C

### Features

- ST advanced rectifier process
- Stable leakage current over reverse voltage
- Reduced leakage current
- Low forward voltage drop
- High frequency operation

# 1 Characteristics

**Table 2: Absolute ratings (limiting values at 25 °C, per diode, unless otherwise specified)**

Symbol	Parameter		Value	Unit	
V <sub>RRM</sub>	Repetitive peak reverse voltage		60	V	
I <sub>F(RMS)</sub>	Forward rms current		60	A	
I <sub>F(AV)</sub>	Average forward current $\delta = 0.5$ , square wave	T <sub>C</sub> = 130 °C	Per diode	15	A
			Per device	30	
I <sub>FSM</sub>	Surge non repetitive forward current	t <sub>p</sub> = 10 ms sinusoidal	250	A	
T <sub>stg</sub>	Storage temperature range		-65 to +175	°C	
T <sub>j</sub>	Maximum operating junction temperature <sup>(1)</sup>		+150	°C	

**Notes:**

<sup>(1)</sup>(dP<sub>tot</sub>/dT<sub>j</sub>) < (1/R<sub>th(j-a)</sub>) condition to avoid thermal runaway for a diode on its own heatsink.

**Table 3: Thermal resistance parameters**

Symbol	Parameter		Max. value	Unit
R <sub>th(j-c)</sub>	Junction to case	Per diode	1.5	°C/W
		Total	0.9	
R <sub>th(c)</sub>	Coupling		0.3	

**Table 4: Static electrical characteristics, per diode**

Symbol	Parameter	Test conditions		Min.	Typ.	Max.	Unit
I <sub>R</sub> <sup>(1)</sup>	Reverse leakage current	T <sub>j</sub> = 25 °C	V <sub>R</sub> = V <sub>RRM</sub>	-		820	μA
		T <sub>j</sub> = 125 °C		-	30	60	mA
		T <sub>j</sub> = 125 °C	V <sub>R</sub> = 45 V	-	17	34	
V <sub>F</sub> <sup>(2)</sup>	Forward voltage drop	T <sub>j</sub> = 25 °C	I <sub>F</sub> = 3 A	-	0.32	0.36	V
		T <sub>j</sub> = 125 °C		-	0.26	0.30	
		T <sub>j</sub> = 25 °C	I <sub>F</sub> = 7.5 A	-	0.39	0.435	
		T <sub>j</sub> = 125 °C		-	0.37	0.42	
		T <sub>j</sub> = 25 °C	I <sub>F</sub> = 15 A	-	0.49	0.545	
		T <sub>j</sub> = 125 °C		-	0.51	0.57	

**Notes:**

<sup>(1)</sup>Pulse test: t<sub>p</sub> = 5 ms,  $\delta < 2\%$

<sup>(2)</sup>Pulse test: t<sub>p</sub> = 380 μs,  $\delta < 2\%$

To evaluate the conduction losses use the following equation:

$$P = 0.27 \times I_{F(AV)} + 0.02 \times I_{F^2(RMS)}$$

### 1.1 Characteristics (curves)

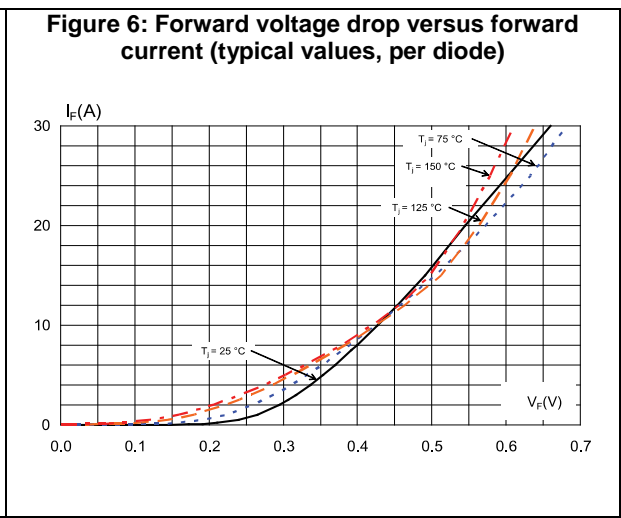
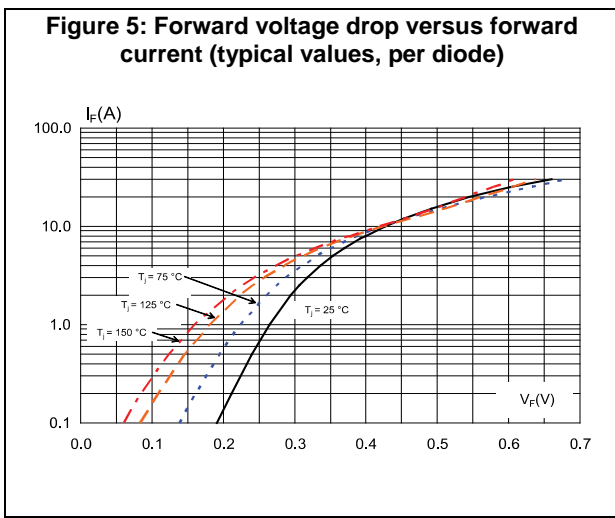
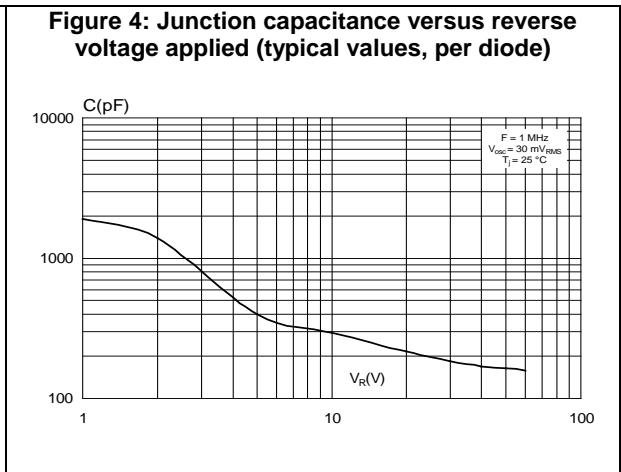
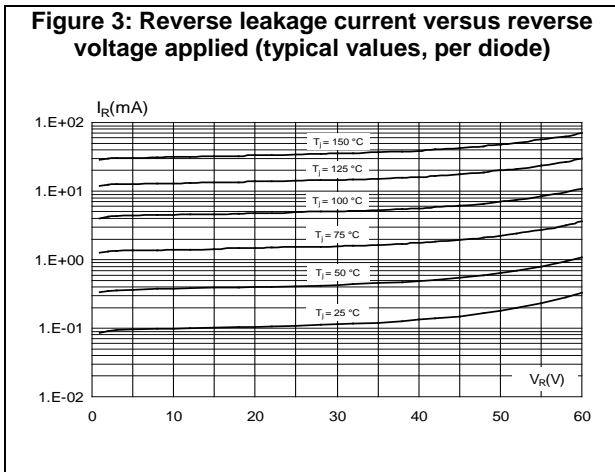
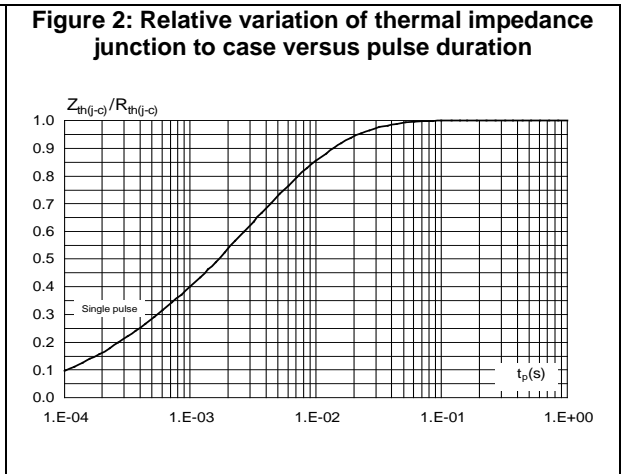
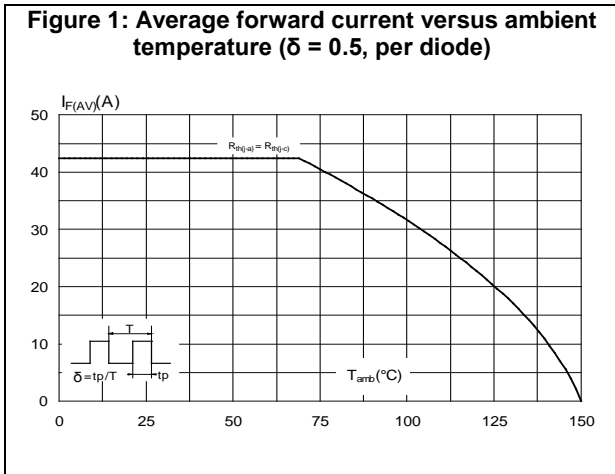
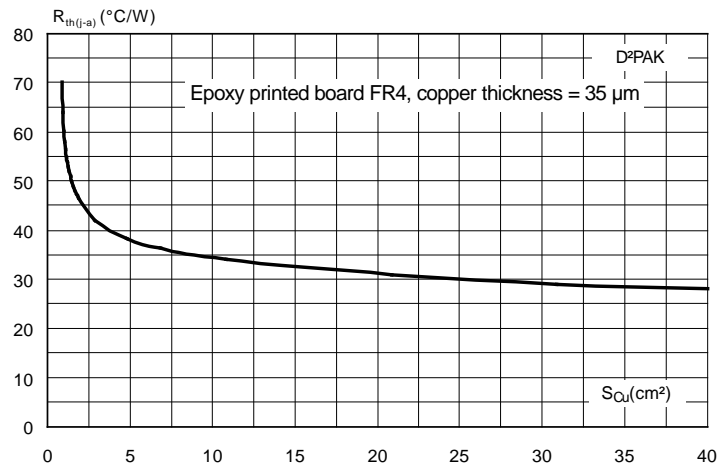


Figure 7: Thermal resistance junction to ambient versus copper surface under tab for D<sup>2</sup>PAK (typical values)



## 2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK® is an ST trademark.

- Cooling method: by conduction (C)
- Epoxy meets UL94,V0
- Recommended torque value: 0.55 N·m (for TO-220AB)
- Maximum torque value: 0.6 N·m (for TO-220AB)

### 2.1 TO-220AB package information

Figure 8: TO-220AB package outline

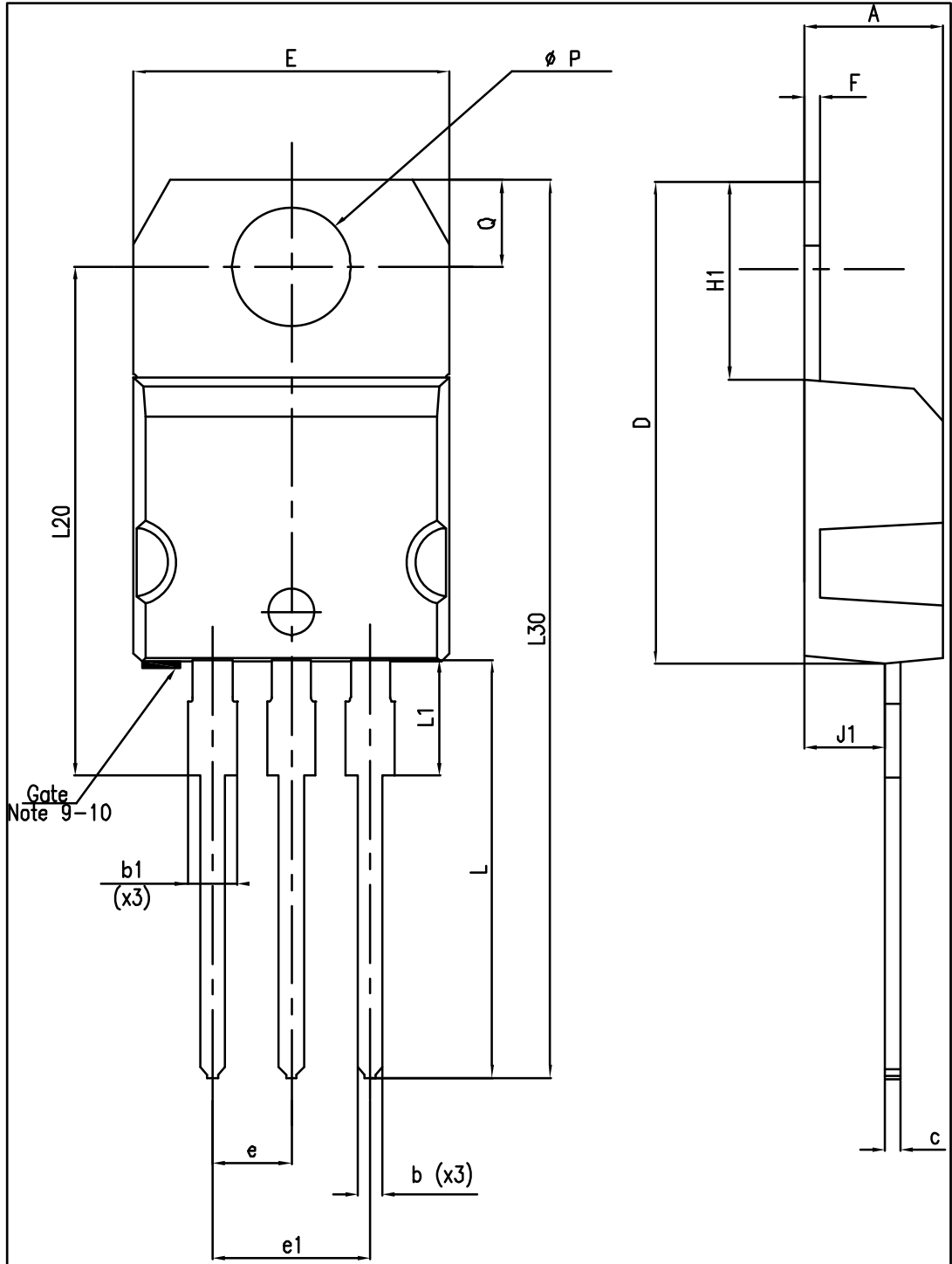


Table 5: TO-220AB package mechanical data

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
b	0.61	0.88	0.024	0.035
b1	1.14	1.70	0.045	0.067
c	0.48	0.70	0.019	0.028
D	15.25	15.75	0.600	0.620
E	10.00	10.40	0.394	0.409
e	2.40	2.70	0.094	0.106
e1	4.95	5.15	0.195	0.203
F	0.51	0.60	0.020	0.024
J1	2.40	2.72	0.094	0.107
H1	6.20	6.60	0.244	0.256
L	13.00	14.00	0.512	0.551
L1	3.50	3.93	0.138	0.155
L20	16.40 typ.		0.646 typ.	
L30	28.90 typ.		1.138	
Ø P	3.75	3.85	0.148	0.156
Q	2.65	2.95	0.104	0.116

## 2.2 D<sup>2</sup>PAK package information

Figure 9: D<sup>2</sup>PAK package outline

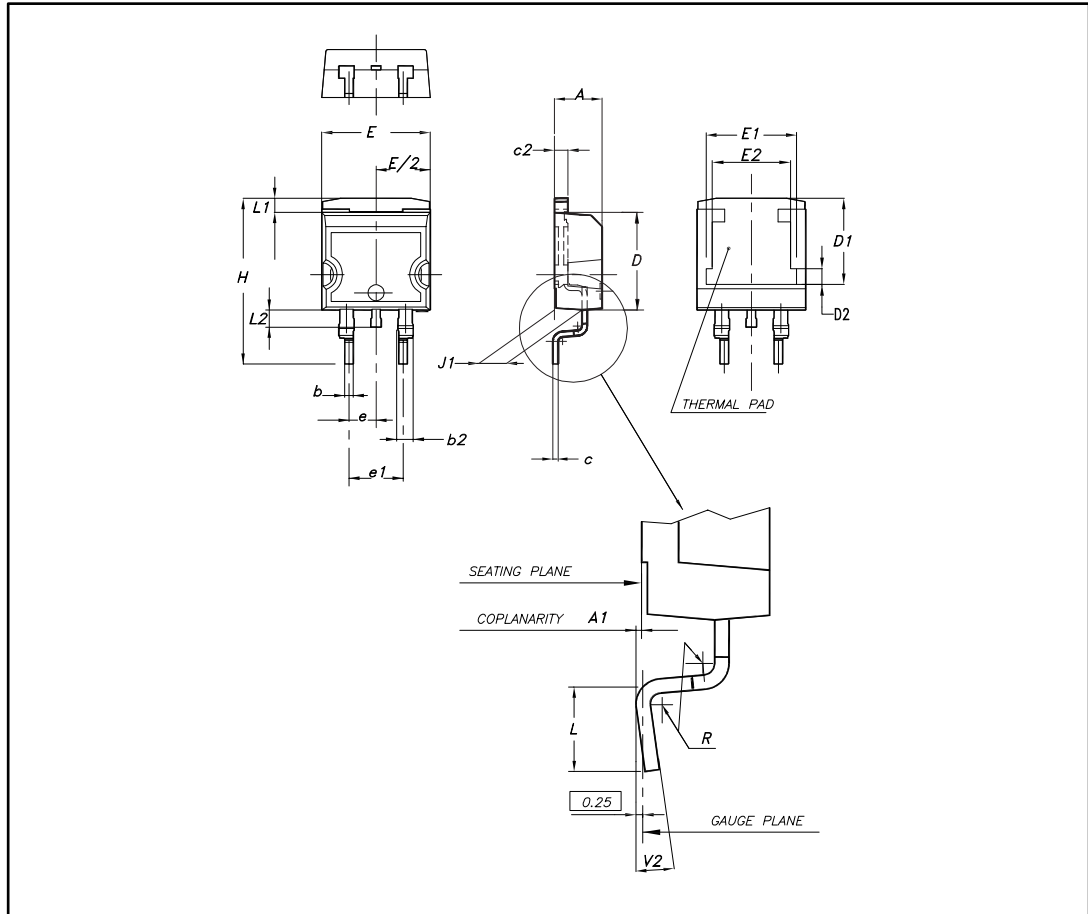
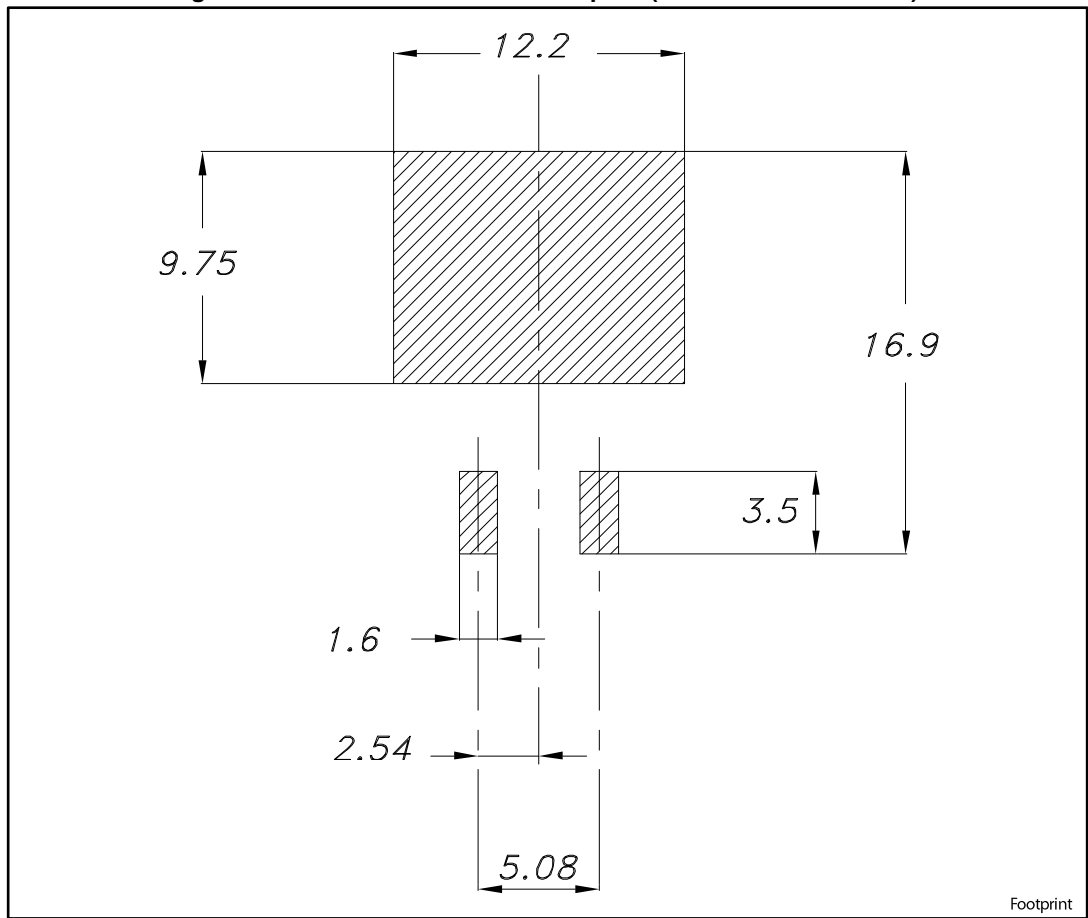




Table 6: D<sup>2</sup>PAK package mechanical data

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.40		4.60	0.173		0.181
A1	0.03		0.23	0.001		0.009
b	0.70		0.93	0.028		0.037
b2	1.14		1.70	0.045		0.067
c	0.45		0.60	0.018		0.024
c2	1.23		1.36	0.048		0.053
D	8.95		9.35	0.352		0.368
D1	7.50	7.75	8.00	0.295	0.305	0.315
D2	1.10	1.30	1.50	0.043	0.051	0.060
E	10		10.40	0.394		0.409
E1	8.50	8.70	8.90	0.335	0.343	0.346
E2	6.85	7.05	7.25	0.266	0.278	0.282
e		2.54			0.100	
e1	4.88		5.28	0.190		0.205
H	15		15.85	0.591		0.624
J1	2.49		2.69	0.097		0.106
L	2.29		2.79	0.090		0.110
L1	1.27		1.40	0.049		0.055
L2	1.30		1.75	0.050		0.069
R		0.4			0.015	
V2	0°		8°	0°		8°

Figure 10: D<sup>2</sup>PAK recommended footprint (dimensions are in mm)



### 3 Ordering information

Table 7: Ordering information

Order code	Marking	Package	Weight	Base qty.	Delivery mode
FERD30L60CTS	FD30L60CTS	TO-220AB	1.38 g	50	Tube
FERD30L60CG-TR	FD30L60CG	D <sup>2</sup> PAK	1.43 g	1000	Tape and reel

### 4 Revision history

Table 8: Document revision history

Date	Revision	Changes
01-Sep-2017	1	Initial release.

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